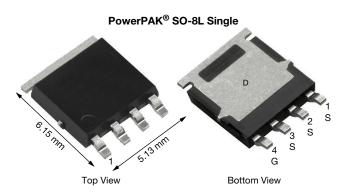


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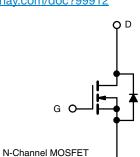
# Automotive N-Channel 100 V (D-S) 175 °C MOSFET



PRODUCT SUMMARY	
V <sub>DS</sub> (V)	100
$R_{DS(on)}(\Omega)$ at $V_{GS} = 10 \text{ V}$	0.0210
$R_{DS(on)}$ ( $\Omega$ ) at $V_{GS} = 4.5 \text{ V}$	0.0258
I <sub>D</sub> (A)	42
Configuration	Single

#### **FEATURES**

- TrenchFET® power MOSFET
- AEC-Q101 qualified <sup>d</sup>
- 100 % Rq and UIS tested
- · Material categorization: for definitions of compliance please see www.vishay.com/doc?99912







COMPLIANT HALOGEN **FREE** 

ORDERING INFORMATION	
Package	PowerPAK SO-8L
Lead (Pb)-free and halogen-free	SQJ488EP (for detailed order number please see <a href="https://www.vishay.com/doc?79771">www.vishay.com/doc?79771</a> )

PARAMETER		SYMBOL	LIMIT	UNIT	
Drain-source voltage		V <sub>DS</sub>	100	V	
Gate-source voltage		V <sub>GS</sub>	± 20	V	
Continuous drain current	T <sub>C</sub> = 25 °C <sup>a</sup>	1	42		
	T <sub>C</sub> = 125 °C	I <sub>D</sub>	24		
Continuous source current (diode conduction	on) <sup>a</sup>	Is	60	Α	
Pulsed drain current <sup>b</sup>		I <sub>DM</sub>	170		
Single pulse avalanche current		I <sub>AS</sub>	5.8		
Single pulse avalanche energy	L = 0.1 mH	E <sub>AS</sub>	1.68	mJ	
Maximum power dissipation <sup>b</sup>	T <sub>C</sub> = 25 °C	D	83	W	
	T <sub>C</sub> = 125 °C	$P_{D}$	27		
Operating junction and storage temperature range		T <sub>J</sub> , T <sub>stg</sub>	-55 to +175	°C	
Soldering recommendations (Peak temperature) e, f			260	°C	

THERMAL RESISTANCE RATINGS				
PARAMETER		SYMBOL	LIMIT	UNIT
Junction-to-ambient F	PCB mount c	R <sub>thJA</sub>	65	°C/W
Junction-to-case (drain)		$R_{thJC}$	1.8	C/VV

- a. Package limited
- b. Pulse test; pulse width  $\leq$  300  $\mu$ s, duty cycle  $\leq$  2 %
- c. When mounted on 1" square PCB (FR-4 material)
- d. Parametric verification ongoing
- See solder profile (<a href="https://www.vishay.com/doc?73257">www.vishay.com/doc?73257</a>). The PowerPAK SO-8L is a leadless package. The end of the lead terminal is exposed copper (not plated) as a result of the singulation process in manufacturing. A solder fillet at the exposed copper tip cannot be guaranteed and is not required to ensure adequate bottom side solder interconnection
- f. Rework conditions: manual soldering with a soldering iron is not recommended for leadless components



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PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT
Static		•				ı	ı
Drain-source breakdown voltage	V <sub>DS</sub>	V <sub>GS</sub>	= 0, I <sub>D</sub> = 250 μA	100	-	-	V
Gate-source threshold voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_{D} = 250 \ \mu A$		1.5	2.0	2.5	V
Gate-source leakage	I <sub>GSS</sub>	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$		-	-	± 100	nA
		V <sub>GS</sub> = 0 V	V <sub>DS</sub> = 100 V	-	-	1	
Zero gate voltage drain current	I <sub>DSS</sub>	V <sub>GS</sub> = 0 V	V <sub>DS</sub> = 100 V, T <sub>J</sub> = 125 °C	-	-	50	μΑ
		V <sub>GS</sub> = 0 V	V <sub>DS</sub> = 100 V, T <sub>J</sub> = 175 °C	-	-	150	1
On-state drain current a	I <sub>D(on)</sub>	V <sub>GS</sub> = 10 V	$V_{DS} \ge 5 V$	30	-	-	Α
		V <sub>GS</sub> = 10 V	I <sub>D</sub> = 7.1 A	-	0.0176	0.0210	
Drain activas an atata registance 3	В	V <sub>GS</sub> = 4.5 V	I <sub>D</sub> = 6.4 A	-	0.0215	0.0258	
Drain-source on-state resistance <sup>a</sup>	R <sub>DS(on)</sub>	V <sub>GS</sub> = 10 V	I <sub>D</sub> = 7.1 A, T <sub>J</sub> = 125 °C	-	-	0.0360	Ω
		V <sub>GS</sub> = 10 V	I <sub>D</sub> = 7.1 A, T <sub>J</sub> = 175 °C	-	-	0.0450	
Forward transconductance b	9 <sub>fs</sub>	V <sub>DS</sub>	= 15 V, I <sub>D</sub> = 7.1 A	-	28	-	S
Dynamic <sup>b</sup>							
Input capacitance	C <sub>iss</sub>			-	782	978	
Output capacitance	C <sub>oss</sub>	$V_{GS} = 0 V$	$V_{DS} = 50 \text{ V}, f = 1 \text{ MHz}$	-	372	462	pF
Reverse transfer capacitance	C <sub>rss</sub>	7		-	44	55	
Total gate charge <sup>c</sup>	Qg			-	18	27	
Gate-source charge	Q <sub>gs</sub>	V <sub>GS</sub> = 10 V	$V_{DS} = 50 \text{ V}, I_{D} = 15 \text{ A}$	-	2	-	nC
Gate-drain charge <sup>c</sup>	Q <sub>gd</sub>	7		-	4.7	-	
Gate resistance	$R_g$		f = 1 MHz	1.1	2.2	3.3	Ω
Turn-on delay time <sup>c</sup>	t <sub>d(on)</sub>			-	4	6	
Rise time <sup>c</sup>	t <sub>r</sub>	$V_{\mathrm{DD}}$	= 50 V, $R_L = 5 \Omega$	-	11	16	
Turn-off delay time <sup>c</sup>	t <sub>d(off)</sub>	$I_D \cong 1 A$	$V_{GEN} = 10 \text{ V}, R_g = 6 \Omega$	-	20	30	ns
Fall time <sup>c</sup>	t <sub>f</sub>	1		-	4.6	7	1
Source-Drain Diode Ratings and Char	racteristics <sup>b</sup>	•			•		
Pulsed current <sup>a</sup>	I <sub>SM</sub>			-	-	128	Α
Forward voltage	V <sub>SD</sub>	l <sub>F</sub> :	= 4.7 A, V <sub>GS</sub> = 0	-	0.78	1.2	V

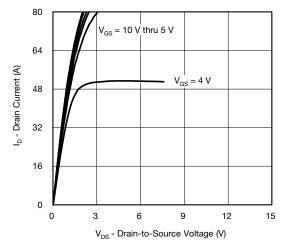
#### Notes

- a. Pulse test; pulse width  $\leq$  300  $\mu$ s, duty cycle  $\leq$  2 %
- b. Guaranteed by design, not subject to production testing
- c. Independent of operating temperature

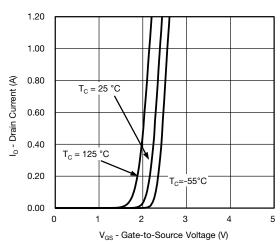
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



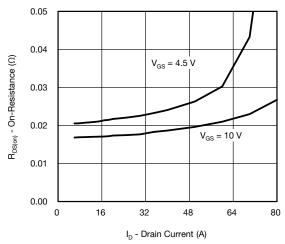
### **TYPICAL CHARACTERISTICS** (T<sub>A</sub> = 25 °C, unless otherwise noted)



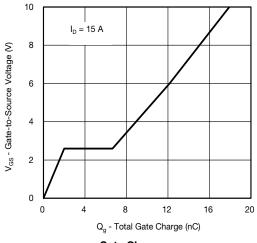
#### **Output Characteristics**



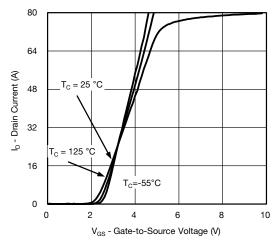
### Transfer Characteristics



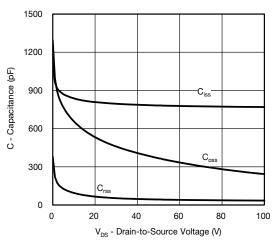
On-Resistance vs. Drain Current



#### **Gate Charge**



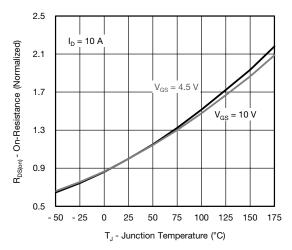
#### **Transfer Characteristics**



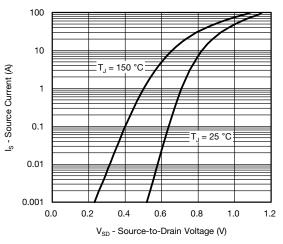
Capacitance



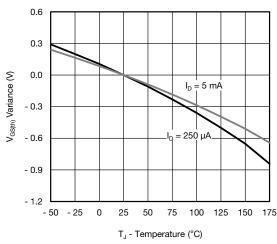
### **TYPICAL CHARACTERISTICS** (T<sub>A</sub> = 25 °C, unless otherwise noted)



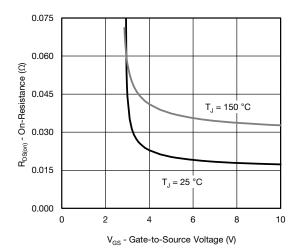
#### On-Resistance vs. Junction Temperature



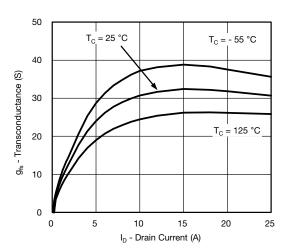
#### **Source Drain Diode Forward Voltage**



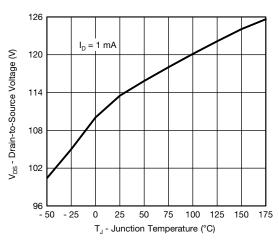
**Threshold Voltage** 



On-Resistance vs. Gate-to Source Voltage



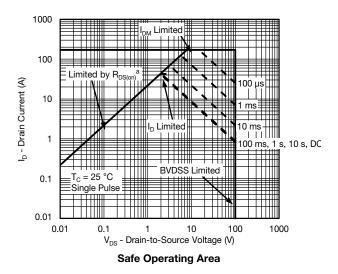
Transconductance



**Drain Source Breakdown vs. Junction Temperature** 

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### **TYPICAL CHARACTERISTICS** ( $T_A = 25$ °C, unless otherwise noted)

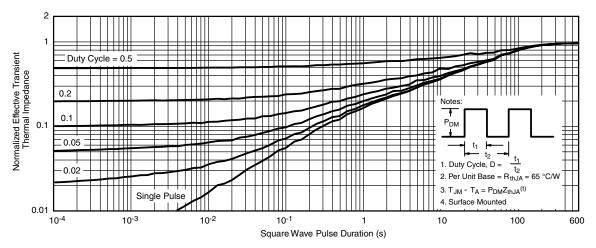


#### Note

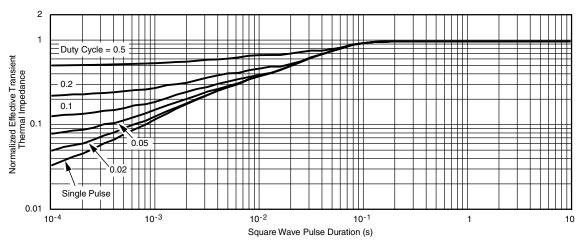
a.  $V_{GS} > minimum \ V_{GS}$  at which  $R_{DS(on)}$  is specified



### **TYPICAL CHARACTERISTICS** (T<sub>A</sub> = 25 °C, unless otherwise noted)



Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Case

#### Note

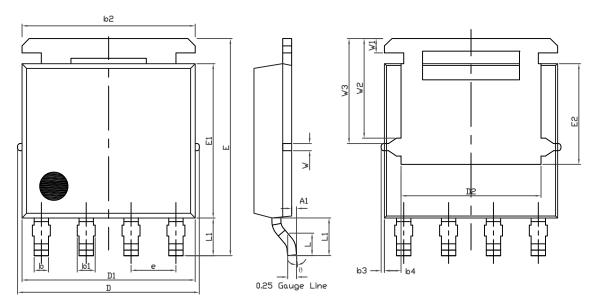
- The characteristics shown in the two graphs
  - Normalized Transient Thermal Impedance Junction-to-Ambient (25 °C)
  - Normalized Transient Thermal Impedance Junction-to-Case (25 °C)

are given for general guidelines only to enable the user to get a "ball park" indication of part capabilities. The data are extracted from single pulse transient thermal impedance characteristics which are developed from empirical measurements. The latter is valid for the part mounted on printed circuit board - FR4, size 1" x 1" x 0.062", double sided with 2 oz. copper, 100 % on both sides. The part capabilities can widely vary depending on actual application parameters and operating conditions

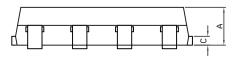
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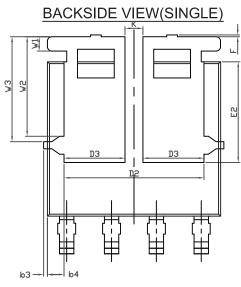


# PowerPAK® SO-8L Case Outline 2



**TOPSIDE VIEW** 





BACKSIDE VIEW(DUAL)



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DIM		MILLIMETERS		INCHES			
DIM.	MIN.	NOM.	MAX.	MIN. NOM.		MAX.	
Α	1.00	1.07	1.14	0.039	0.042	0.045	
A1	0.00	-	0.127	0.00	-	0.005	
b	0.33	0.41	0.48	0.013	0.016	0.019	
b1	0.44	0.51	0.58	0.017	0.020	0.023	
b2	4.80	4.90	5.00	0.189	0.193	0.197	
b3		0.094		0.004			
b4		0.47			0.019		
С	0.20	0.25	0.30	0.008	0.010	0.012	
D	5.00	5.13	5.25	0.197	0.202	0.207	
D1	4.80	4.90	5.00	0.189	0.193	0.197	
D2	3.86	3.96	4.06	0.152	0.156	0.160	
D3	1.63	1.73	1.83	0.064	0.068	0.072	
е		1.27 BSC		0.050 BSC			
Е	6.05	6.15	6.25	0.238	0.242	0.246	
E1	4.27	4.37	4.47	0.168	0.172	0.176	
E2	2.75	2.85	2.95	0.108	0.112	0.116	
F	-	-	0.15	-	-	0.006	
L	0.62	0.72	0.82	0.024	0.028	0.032	
L1	0.92	1.07	1.22	0.036	0.042	0.048	
K		0.51			0.020		
W		0.23			0.009		
W1		0.41			0.016		
W2	2.82			0.111			
W3		2.96			0.117		
q	0°	-	10°	0°	-	10°	

ECN: S19-0643-Rev. B, 05-Aug-2019

DWG: 6044

#### Note

· Millimeters will gover



### RECOMMENDED MINIMUM PAD FOR PowerPAK® SO-8L SINGLE



Recommended Minimum Pads Dimensions in mm (inches)



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